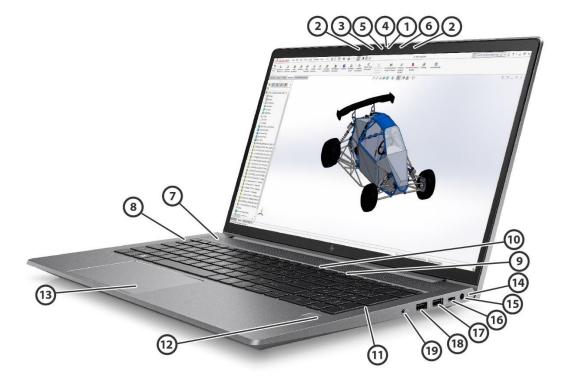
Overview

HP ZBook Power 15.6" G9 Mobile Workstation PC



- 1. Ambient Light Sensor
- 2. Internal Microphones (optional)
- 3. Camera LEDs (optional)
- 4. Camera LEDs (optional)
- 5. IR Camera (optional)
- 6. Camera Cover
- 7. Speakers
- 8. Function Keys (changes with configured options)
- 9. Power button
- 10. HP Programmable Key

Right

- 11. Numeric Keypad
- 12. Fingerprint Sensor (optional)
- 13. Touchpad
- 14. Indicator LEDs: Power light, Wireless light, Storage usage light
- 15. Power connector
- 16. USB Type-C[®] with Thunderbolt[™] 4
- 17. USB 3.1 Gen 1
- 18. USB 3.1 Gen 1
- 19. Audio Combo Jack



Overview



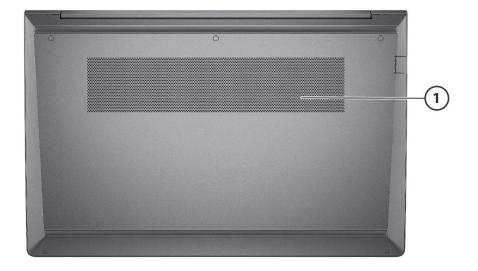
Left

- 1. Nano Security lock slot
- 2. RJ-45
- 3. USB 3.1 Gen 1 Charging Port

- 4. HDMI port
- 5. Smart Card Reader



Overview



Bottom

1. Fan Venting



Overview

At A Glance

- Work without compromising on performance or security with Windows 10 Pro and HP's collaboration and connectivity technology.
- NVIDIA Professional GPUs provide the interactive visual workspace you need to do great work wherever, whenever. With twice
 the CUDA cores as previous generations, NVIDIA Professional GPUs deliver the performance professionals need to work from
 anywhere.
- Take multitasking to the next level with 12th gen Intel[®] Core[™] i9 processors built to handle multithreaded apps like Adobe Premiere Pro[®], and with fast clock speeds to boost your speed on single threaded apps like Autodesk 3ds Max.
- Strenuously tested to meet ISV certification and deliver superb performance and support with leading software providers, including Autodesk and Adobe[®].
- Have confidence with HP's and defend against firmware and malware attacks with HP Sure Start and Sure Sense.
- Built with the environment in mind, this ZBook includes recycled ocean-bound plastics, plastic-free packaging, and ultraefficient power consumption.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt[™] Dock for lightning fast Thunderbolt[™] 4 transfers and the flexibility to run up to 1 external 4K and 1 external 5K.
- Work without limits in any location with up to 8TB of local PCIe storage.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled OSWindows 11 Pro - HP recommends Windows 11 Pro for business 2
Windows 11 Home - HP recommends Windows 11 Pro 2
Windows 11 Home Single Language - HP recommends Windows 11 Pro 2
Windows 10 Pro (available through downgrade rights from Windows 11 Pro)1,2,3
FreeDOS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

PROCESSOR

12th Generation Intel[®] Core[™] i9-12900H with Intel[®] Iris[®] Xe Graphics (1.8 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo Frequency, up to 5.0 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 Threads), supports Intel[®] vPro[®] Technology ^{1,2,3,4,5}

12th Generation Intel[®] Core[™] i9-12900HK with Intel[®] Iris[®] Xe Graphics (1.8 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo Frequency, up to 5.0 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 Threads) ^{1,2,3,4}

12th Generation Intel[®] Core[™] i7-12800H with Intel[®] Iris[®] Xe Graphics (1.8 GHz E-core base frequency, 2.4 GHz P-core base frequency, up to 3.7 GHz E-core Max Turbo Frequency, up to 4.8 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 Threads), supports Intel[®] vPro[®] Technology ^{1,2,3,4,5}

12th Generation Intel[®] Core[™] i7-12700H with Intel[®] Iris[®] Xe Graphics (1.7 GHz E-core base frequency, 2.3 GHz P-core base frequency, up to 3.5 GHz E-core Max Turbo Frequency, up to 4.7 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 Threads), supports Intel[®] vPro[®] Technology ^{1,2,3,4,5}

12th Generation Intel[®] Core[™] i5-12600H with Intel[®] Iris[®] Xe Graphics (2.0 GHz E-core base frequency, 2.7 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.5 GHz P-core Max Turbo frequency, 18MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads), supports Intel[®] vPro[®] Technology^{1,2,3,4,5}

12th Generation Intel[®] Core[™] i5-12500H with Intel[®] Iris[®] Xe Graphics (1.8 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.5 GHz P-core Max Turbo frequency, 18MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads) ^{1,2,3,4}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.



Features

³ Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro



Features

CHIPSET

Chipset is integrated with processor

INTEL[®] CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel[®] Core[™] i5 with vPro[®], Core[™] i7 with vPro[®], Core[™] i9 with vPro[®] technology is a selectable feature that is available on units configured with select processors, a qualified Intel[®] WLAN module and a preinstalled Windows[®] operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel[®] Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.^{1,2}

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro, see data sheet

GRAPHICS

Integrated

Intel[®] Iris[®] Xe Graphics ^{1, 3, 4, 5, 6}

Discrete

NVIDIA Graphic options: NVIDIA RTX[™] A2000 Laptop GPU (8 GB GDDR6 dedicated) ^{1,2,3,4,5} NVIDIA RTX[™] A1000 Laptop GPU (4 GB GDDR6 dedicated) ^{1,2,3,4,5} NVIDIA T600 Laptop GPU (4 GB GDDR6 dedicated) ^{1,2,3,4,5}

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.3

¹ UHD content required to view UHD images.

² Both UMA & Discrete configurations support 4 independent displays when on the HP Thunderbolt Dock G2 (120W) (sold separately) - Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C output port using a Type C-to-DP adapter).

³ Support HD decode, DX12, HDMI 2.0b, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4096x2304 @ 60Hz ⁴ HDMI cable Sold Separately

⁵ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁶ Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

DISPLAY

Non-touch



Features

- 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR bent NWBZ
- 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZ
- 15.6 inch UHD (3840x2160) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NB2Y

Touch

• 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ

DisplayPort™ 1.2

HDMI 2.0 Support resolution up to 4K @60 Hz

Displays support

Supports dual display through the dock

¹HD content required to view HD images.
²Sold separately or as an optional feature.
³Resolutions are dependent upon monitor capability, and resolution and color depth settings.
⁴HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

⁵Actual brightness will be lower with touchscreen or Sure View.



Features

DOCKING

Docking station model #1	HP Thunderbolt Dock G2
Total number of supported displays (incl.the notebook) display)	4
Max.resolutions supported	Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported Single 8K@ 30Hz (multiple tiles) for Thunderbolt hosts Non-TBT hosts DP 1.4 in high res mode(1) 8K video single cable@30Hz
Dock Connectors	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode
Technical limitations	 Thunderbolt Hosts: Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host. Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode @30Hz Non-Thunderbolt hosts: The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.
Docking station model #2	HP USB-C Dock G5
Total number of supported displays (incl.the notebook) display)	3
Max.resolutions supported	Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode)
Dock Connectors	1xHDMI, 2xDP
Technicallimitations	Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port .
Docking station model #3	HP USB-C/A Universal Dock G2
Total number of supported displays (incl.the notebook) display)	3
Max.resolutions supported	Triple 4K UHD@ 60Hz
Dock Connectors	1xHDMI, 2xDP
Technicallimitations	The best resolution for dual or triple displays is 4K UHD@ 60Hz. For use with the USB-A adapter that comes in the box the maximum number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the host



Features

STORAGE AND DRIVES*

Max Storage

8TB through two m.2 NVMe drivers

(Up to 2) m.2 storage (NVMe PCIe Gen4 SSDs)

PCIe[®] NVMe[™] M.2 2280 Storage

4 TB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC 2 TB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC 1 TB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC 512 GB PCIe[®] Gen4x4 NVMe[™] SED TLC OPAL2 512 GB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC 256 GB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC 256 GB PCIe[®] Gen4x4 NVMe[™] SED TLC OPAL2

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe) RAID: PCle[®] Gen4 x4 lanes NVMe[™] Solid State Drive RAID 0/1 is supported (and available from factory)

MEMORY

Maximum Memory

64GB DDR5-4800 Memory

Memory 64GB DDR5-4800 (2x32GB) 32GB DDR5-4800 (2x16GB) 32GB DDR5-4800 (1x32GB) 16GB DDR5-4800 (2x8GB) 16GB DDR5-4800 (1x16GB) 8GB DDR5-4800 (1x8GB)

Memory Slots

2 SODIMM DDR5 SODIMMS, system runs at 4800 Supports Dual Channel Memory

¹ Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



Features

NETWORKING/COMMUNICATIONS

WLAN¹

Intel® AX211 Wi-Fi6E+BT5.2 M.2 1216 160MHz CNVi World-Wide WLAN vPro Intel® AX211 Wi-Fi6E +BT5.2 M.2 1216 160MHz CNVi World-Wide WLAN non-vPro

¹ Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Near Field Communication (NFC) module No Near Field Communication (NFC) module NFC Mirage WNC XRAV-1

Miracast

Native Miracast Support

NOTE: Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Discrete Amplifiers Integrated dual array microphone

Speaker Power

2W/4ohm Per speaker

Camera^{1, 2}

720p HD camera with IR 720p HD camera

Sensors

ALS (ambient light sensor) Magnetometer Hall Sensor Gyro Accelerometer HP Tamper Lock³

¹ HD content required to view HD images.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport. ³ HP Tamper Lock must be enabled by the customer or your administrator.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard*

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Non-Backlit keyboard and DuraKeys

Pointing Devices

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Command Center home end Power Button (with LED) delete **Hidden Keys** Fn+R - Break Fn+S - Sys Rg Fn+C - Scroll Lock

*Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

Software

HP Ouick Touch HP Quick Drop²¹ **HP Easy Clean HP PC Hardware Diagnostics Windows HSA Fusion for Commercial** HSA Telemetry for Commercial **Touchpoint Customizer for Commercial myHP** Tile App^{22,25} HP Smart Support²⁴ HP Connection Optimizer¹⁰ HP Mac Address Manager **HP Hotkey Support** HP Support Assistant¹ **HP** Notifications **HP Privacy Settings HP Power Manager** Buy Microsoft Office (Sold separately)



Features

Manageability Features

HP Connect for Microsoft Endpoint Manager²⁶ HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download)¹² HP Client Management Script Library (download) HP Patch Assistant (download)²⁷ HP Driver Packs (download) HP Cloud Recovery ²⁸ HP Client Catalog (download)

Security Management

HP Wolf Security of Business ²⁹ includes:

HP Sure Click ³⁰ HP Sure Sense¹⁹ HP Sure Run Gen5³¹ HP Sure Recover Gen5¹⁴ HP Sure Start Gen7¹⁶ HP Tamper Lock HP Sure Admin²³ HP Client Security Manager Gen7¹⁸

BIOS

HP BIOSphere Gen6⁶ HP Secure Erase¹⁷ Absolute Persistence Module⁷ HP DriveLock & Automatic DriveLock BIOS Update via Network HP Wake on WLAN HP Fingerprint Sensor³² Secured-Core PC Enable²⁰ TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

¹ HP Support Assistant - Requires Windows and Internet Access.

⁶ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

⁷ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

¹⁰ HP Connection Optimizer requires Windows 10 and beyond version.

¹² HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

¹⁴ HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module

¹⁵ HP Sure Recover with Embedded Reimaging Gen3 is an optional feature which must be configured at purchase with a base unit that has the On System Recovery (OSR) module . See product specifications for availability You must back up important files, data, photos, videos, etc. before use to avoid loss of data. HP Sure Recover with Embedded Reimaging (Gen1) does not support platforms with Intel[®] Optane[™]. ¹⁶ HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher

¹⁷ HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

¹⁸ HP Client Security Manager Gen7 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.



Features

¹⁹ HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS. ²⁰ Secured-core PC requires an Intel[®] vPro[®] or AMD Ryzen[™] Pro processor. Requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.

²¹ Requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

²² Some features require

optional subscription to Tile Premium. Tile application for Windows 10

available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778

for more information. HP Tile will function as long as the PC has battery power.

²³ HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

²⁴ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

²⁵ Some Tile features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. Tile will function as long as the PC has battery power.

²⁶ HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.
 ²⁷ HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

²⁸ HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

²⁹ HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.

³⁰ HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

³¹ HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.

³² HP Fingerprint Reader is an optional feature that requires Windows 10 IoT and must be configured at purchase.



Features

POWER

Power Supply

120 W Slim Smart external AC power adapter³ 150 W Slim Smart external AC power adapter⁴

Battery

HP Long Life 6-cell, 83 Wh Polymer

Power Cord 3-wire plug - 1m 2-wire plug - 1m

Battery life Up to 18 hrs

Supports Battery fast charge approximately 50% in 30 minutes (defined under system hibernation and off mode).

¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark https://bapco.com/products/mobilemark-2018/ for additional details.
 ² Supports HP Fast Charge Technology
 ³Only available with UMA graphics
 ⁴ Only available with discrete graphic options
 ⁵Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other

factors.

ENVIRONMENTAL

ENERGY STAR® certified EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. EPEAT® 2019 Gold¹ TCO 8.0 Certified RCTA DO-160G SEPA GS Mark Eyesafe Certification - Worldwide

Sustainable Impact Specifications

Recycled Aluminum and Magnesium, 75% PCR w/30% ITE plastics

¹ Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit www.epeat.net for more information.



Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.94 x 23.39 x 2.28 cm 14.15 x 9.21 x 0.9 in

Weights*

Starting at 1.9kg (4.16 lb) Weight varies by configuration and components. A deck: Anodized Aluminum B deck: PC-ABS with Talc C deck: Anodized Aluminum D deck: Anodized Aluminum Metal Alloy Hinges

*Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Left side

1 RJ-45 1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging] 1 HDMI1,2 1 smart card reader 1 Nano Security Lock Slot

Right side

1 power connector 1 Audio Combo Jack 1 USB Type-C[®] (Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4, HP Sleep and Charge) 2 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]

*SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4. *HDMI cable sold separately.

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Features

SYSTEM UNIT

JIJIENON			
Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	AC 20V	
	Average Operating		System in idle mode
	Power(idle)	WIN10	UMA 2.3W
			DIS 2.6W
	Integrated graphics	Yes	
	Discrete Graphics	N/A	
	Max Operating Power	UMA<65W	
Temperature	Operating	32° to 95° F (0° to 3	35° C)
	Non-operating	41° to 95° F (5° to 3	35° C) (writing optical)
Relative Humidity	Operating	10% to 90%, non-	condensing
	Non-operating	5% to 95%, 101.6°	°F (38.7°C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-si	ne
	Non-operating	200 G, 2 ms, half-s	sine
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Maximum Altitude	Operating	-50 to 10,000 ft (-	15.24 to 3,048 m)
(unpressurized)	Non-operating	-50 to 40,000 ft (-	15.24 to 12,192 m)
Temperature Derating with Altitude	Operating	1.8°F / 1000 ft (1°(C / 304.8 m)
Planned Industry Standard Certifications	Regulatory Model Number	HSN-145C-3	
	UL	Yes	
	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Certified ¹	
	EPEAT®	EPEAT 2.0 Gold ²	
	ICES	Yes	
	Australia / NZ A-Tick Compliance	Yes	
	כככ	Yes	
	Japan VCCI Compliance	Yes	
	КСС	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	MIL STD 810H	Yes, 19 tests	
	BNCI or BELUS	Yes	
	CIT	Yes	
	EAC	Yes	
	Saudi Arabian Compliance (ICCP)	Yes	
	SABS	Yes	

¹Configurations of the HP ZBook Power 15.6" G9 Mobile Workstation PC that are ENERGY STAR[®] qualified are identified as HP ZBook Power 15.6" G9 Mobile Workstation PC ENERGY STAR on HP websites and on http://www.energystar.gov.



Features

² Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit www.epeat.net for more information.

Technical Specifications – Displays

DISPLAYS

Panel LCD 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR bent NWBZ

Outline Dimensions (W × H) Active Area	350.96 x 205.54 mm (344.16 x 193.59 mm (
Weight	370 g (max)	ι υμ.)
Diagonal Size	15.6 inch	
Thickness	3.0 mm/ 5.0 mm (w/P	CB) (max)
Interface	eDP 1.2 (2 lane)	
Surface Treatment	Anti-Glare	
Touch enabled	No	
Contrast Ratio	600:1 (typ.)	
Refresh Rate	60 Hz	
Brightness	250 nits	
Pixel Resolution	Pitch	1920 x 1080 (FHD)
	Format	RGB Stripe
Backlight	LED	
Color Gamut Coverage	NTSC 45%	
Color Depth	6 bits (Hi FRC supporti	ive w/ condition to enable)
Viewing Angle	UWVA 85/85/85/85	

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

350.96 x 205.74 mm (max)

Panel LCD 15.6 inch FHD
(1920x1080) Anti-Glare
WLED UWVA 45percent
cg 250nits eDP 1.2 w/o
PSR bent Touch on Panel
NWBZOutline Dimensions (W × H)
Active Area
Weight
Diagonal Size
Thickness

Active Area	344.16 x 193.59 mm (1	typ.)
Weight	380 g (max)	
Diagonal Size	15.6 inch	
Thickness	3.2mm/ 5.2mm (PCB) ((max)
Interface	eDP 1.2 (2 lane)	
Surface Treatment	Anti-Glare On-cell	
Touch enabled	Yes	
Contrast Ratio	600:1 (typ.)	
Refresh Rate	60 Hz	
Brightness	250 nits	
Pixel Resolution	Pitch	1920 x 1080 (FHD)
	Format	RGB Stripe
Backlight	LED	
Color Gamut Coverage	NTSC 45%	
Color Depth	6 bits	
Viewing Angle	UWVA 85/85/85/85	

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Displays

Panel LCD 15.6 inch FHD	Out
(1920x1080) Anti-Glare WLED UWVA sRGB	Act
100percent cg 400nits	We
eDP 1.4+PSR2 bent LP	Dia
NWBZ	Thi

Outline Dimensions (W × H)	349 46 x 204 79 mm (m	ax)	
,			
Active Area	344.16 x 193.59 mm (typ.)		
Weight	325 g (max)		
Diagonal Size	15.6 inch		
Thickness	2.6mm / 4.6mm (PCB) (r	max)	
Interface	eDP 1.4 (2 lane)		
Surface Treatment	Anti-Glare		
Touch enabled	No		
Contrast Ratio	1200:1 (typ.)		
Refresh Rate	60 Hz		
Brightness	400 nits		
Pixel Resolution	Pitch	1920 x 1080 (FHD)	
	Format	RGB Stripe	
Backlight	LED		
Color Gamut Coverage	sRGB 100% (NTSC 72%)		
Color Depth	8 bit		
Viewing Angle	UWVA 85/85/85/85		

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 15.6 inch UHD (3840x2160) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NB2Y

Outline Dimensions (W x H)	349.52 x 205.42 mm (max)		
Active Area	344.22 x 193.62 mm (typ.)		
Weight	320 g (max)		
Diagonal Size	15.6 inch		
Thickness	2.6mm / 4.6mm (PCB)	(max)	
Interface	eDP 1.4 (4 lane)		
Surface Treatment	Anti-Glare		
Touch Enabled	No		
Contrast Ratio	1200:1 (typ.)		
Refresh Rate	60 Hz		
Brightness	400 nits		
Pixel Resolution	Pitch	3840 x 2160 (UHD)	
	Format	RGB Stripe	
Backlight	LED		
Color Gamut Coverage	sRGB 100% only for UH	ID LP	
Color Depth	8 bits		
Viewing Angle	UWVA 85/85/85/85		

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Storage

STORAGE AND DRIVES

STORAGE AND DRI			
SSD 256GB 2280 PCIe-4x	4 Form Factor	M.2 2280	
NVMe Three Layer Cell	Capacity	256GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen4X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		4000 MB/s ±20%	2000 MB/s ±20%
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [amb	pient temp]
	Features	Pyrite 2.0; TRIM; L1.2	
			1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for
SSD 512GB 2280 PCIe-	Form Factor	M.2 2280	
4x4 NVMe Three Layer	Capacity	512GB	
Cell	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen4X4	
	IIILEITALE		
	Performance	Maximum Sequential Read	Maximum Sequential Write
			Maximum Sequential Write 3500 MB/s ±20%
		Maximum Sequential Read	-
	Performance	Maximum Sequential Read 6400 MB/s ±20%	3500 MB/s ±20%
	Performance Logical Blocks	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215	3500 MB/s ±20%
	Performance Logical Blocks Operating Temperature	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB =	3500 MB/s ±20%
SSD 1TB 2280 PCIe-4x4	Performance Logical Blocks Operating Temperature	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell	Performance Logical Blocks Operating Temperature Features	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software.	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm)	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm)	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width Weight	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen4X4	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width Weight Interface	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g)	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width Weight Interface	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen4X4 Maximum Sequential Read	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for Maximum Sequential Write
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width Weight Interface Performance	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen4X4 Maximum Sequential Read 6400 MB/s ±20%	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for Maximum Sequential Write 5000 MB/s ±20%
	Performance Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height Width Weight Interface Performance Logical Blocks	Maximum Sequential Read 6400 MB/s ±20% 1,000,215,215 32° to 158°F (0° to 70°C) [amb Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = formatted capacity is less. Up system recovery software. M.2 2280 1TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen4X4 Maximum Sequential Read 6400 MB/s ±20% 2,000,409,264	3500 MB/s ±20% ient temp] 1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for Maximum Sequential Write 5000 MB/s ±20%



Technical Specifications – Storage

SSD 27B 2280 PCie-4x4 NWMe Three Layer Cell Capacity 27E NAN DType TLC Height 0.09 in (2.3 mm) Width 0.87 in (2.2 mm) Weight 0.08 in (2.3 mm) Width 0.87 in (2.2 mm) Weight 0.09 in (2.3 mm) Width 0.87 in (2.2 mm) Weight 0.09 in (2.3 mm) Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write Gapacity 23° to 158°F (0° to 70°C) [ambient temp] Features 23° to 158°F (0° to 70°C) [ambient temp] Features 25668 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Solid State Drive Capacity 25668 OPAL2 Three Layer Cell Solid State Drive Maximum Sequential Read Maximum Sequential Write Height Vidth 0.02 in (10 g) Interface 2000 MB/s ±20% Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Read Maximum Sequential Read Maximum Sequential Write H				1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for
NVMe Three Layer Cell Capacity 2TB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe VVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write G400 MB/s 220% S000 MB/s 220% Operating Temperature 22 to 158° f O'to 07O'() (ambient temp) Features Pyrite 2.0; TRIM; L1.2 Mote: For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes. Actual formatted capacity is lass. Up to 35 GB (for Windows 10) is reserved for system recovery software. Z56GB PCIe-0x4 2280 Form Factor MVME SetF Encrypted Capacity Salid State Drive Form Factor Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.87	SSD 2TB 2280 PCIe-4x4	Form Factor	M.2 2280	
NND TypeTLCHeight0.05 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lo (10 g)InterfacePCR VMK Gen4X4PerformanceMaximum Sequential RealMaximum Sequential Write6400 MB/s ± 20%5000 MB/s ± 20%Deperting Temperatur02 to 158° fC 'to 70° C) [arrister Corrego drives, GB = 1 billion bytes, TB = 1 trillion bytes, Actual formatted capacity is less. up to 35 GB for Windows 10) is reserved for system recovery of tware.256GB PCIe-4x4 2280Form FactorN2 2280NVME Self Encrypted Midth0.09 in (2.3 mm)	NVMe Three Layer Cell	Capacity		
F26GB PCIe-4x4 2280 NVME Self Encrypted UP410 0.09 in (2.3 mm) Use NVME Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write G400 MB/s ±20% S56GB PCIe-4x4 2280 Operating Temperature 22* to 158°F (0* to 70°C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S56GB PCIe-4x4 2280 Form Factor M.2 2280 NMME Self Encrypted UP4L2 Three LayerCell Form Factor Maximum Sequential Read Maximum Sequential Write NAND Type T.C Scole Gave Scole Gave Scole Gave Vidith 0.09 in (2.3 mm) Use Storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor No2 US (10 g) NAND Type T.C Nakinum Sequential Read Maximum Sequential Write Goperating Temperature 3000 MB/s ±20% Operating Temperature 2000 MB/s ±20% Upical Blocks Sol,118,192 Operating Temperature 32 Co SGB (Gover, Gave,		• •	TLC	
View Weight0.87 in (22 mm)		••	0.09 in (2.3 mm)	
Interface PCINVMe Cen4X4 Maximum Sequential Real 6400 MB/s ±20% Maximum Sequential Write 5000 MB/s ±20% Logical Blocks 4.000,797,360 Store St		-	0.87 in (22 mm)	
Performance Maximum Sequential Real Maximum Sequential Real Soiton MB/s ±20% Logical Blocks 420 to 158° (0' to 70°() ====================================		Weight	0.02 lb (10 g)	
5600 MB/s ±20% 5000 MB/s ±20% Logical Blocks 4,000,797,360 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. 256GB PCle-4x4 2280 Form Factor M2 2280 QPAL2 Three Layer Cell Form Factor M2 2280 Vidith 0.99 in (2.3 mm) Width 0.99 in (2.3 mm) Width 0.91 in (2.2 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 2000 MB/s ±20% Logical Blocks 500,118,192 2000 MB/s ±20% 2000 MB/s ±20% Deprating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Features Features Form Factor K2 2280 K00 MB/s ±20% <th></th> <th>Interface</th> <th>PCIe NVMe Gen4X4</th> <th></th>		Interface	PCIe NVMe Gen4X4	
Logical Blocks 4,000,797,360 Operating Temperature 22* to 158°F (0* to 70°) [arriteriteriteriteriteriteriteriteriterit		Performance	Maximum Sequential Read	Maximum Sequential Write
S566B PCIe-4x4 2280 NVME 5elf Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280 NVME 5elf Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280 NAND Type TC Height 0.09 in (2.3 mm)			6400 MB/s ±20%	5000 MB/s ±20%
Features Pyrite 2.0; TRIN; L1.2 Note: For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes, Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Z56GB PCle-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Width 0.87 in (22 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Peformance Maximum Sequential Real Maximum Sequential Write 4000 MB/s ±20% 2000 MB/s ±20% 2000 MB/s ±20% Logical Blocks 500,118,192 2000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [ambi=tr temp] Features Features TCG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted Form Factor M.2 2280 OPAL2 Three Layer Cell Gapacity S12GB Solid State Drive Form Factor M.2 2280 NUME Self Encrypted Opacity		Logical Blocks	4,000,797,360	
S56GB PCIe-4x4 2280 OVMEE Self Encrypted OPAL2 Three Layer Cele Form Factor M.2 2280 Solid State Drive Form Factor M.2 2280 VMME Self Encrypted OPAL2 Three Layer Cele Form Factor M.2 2280 VMME Self Encrypted OPAL2 Three Layer Cele Form Factor M.2 2280 VMME Self Encrypted OPAL2 Three Layer Cele Form Factor M.2 2280 VMME Self Encrypted OPAL2 Three Layer Cele O.99 in (2.3 mm)		Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]
S256GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cett Solid State Drive Form Factor M.2 2280 S256GB NAND Type 1LC Height 0.09 in (2.3 mm) S256GB Width 0.87 in (22 mm) S256GB Width 0.02 lb (10 g) Interface Performance Maximus Sequential Read Maximus Sequential Write 4000 MB/s ±20% 2000 MB/s ±20% 2000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [ambinut temp] Features Features Form Factor M.2 2280 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NAND Type TLC MMME Self Encrypted Gapacity S12GB MAND Type TLC Height 0.09 in (2.3 mm) Ture Layer Cettor Mindows 10) is reserved for system recovery software. TUPE Cettor Mindows 10) is reserved for S10 Sis reserved for S10 Sis reserved for S10 Sis res		Features	Pyrite 2.0; TRIM; L1.2	
NVME Self Encrypted OPAL2 Three Layer Cett Solid State Drive Capacity 255GB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write Logical Blocks 500,118,192 2000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [ambi=nt temp] 2000 MB/s ±20% Solid State Drive Features TCG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cett S12GB S12GB Capacity S12GB Solid State Drive Form Factor M.2 2280 S12GB Capacity S12GB Solid State Drive Form Factor M.2 2280 S12GB MAND Type Height 0.02 lb (10 g) Interface Interface NVME Self Encrypted OPAL2 Three Layer Cett S12GB S12GB S10 MS ± 20% <			formatted capacity is less. Up	
OPAL2 Three Layer Cell Solid State Drive NAND Type TLC Height 0.09 in (2.3 mm) Height Width 0.87 in (22 mm) Width Weight 0.02 lb (10 g) Interface Performance Maximum Sequential Read Maximum Sequential Write Logical Blocks 500,118,192 2000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [amburt temp] 2000 MB/s ±20% Features TCG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cell NAND Type TLC Height 0.09 in (2.3 mm) Width Width 0.87 in (22 mm) S12GB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) SIG (for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 SIG (for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 SIG (for Windows 10) i		Form Factor	M.2 2280	
Solid State Drive NAND Type ILC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write 4000 MB/s ±20% 2000 MB/s ±20% 2000 MB/s ±20% Logical Blocks 500,118,192 2000 MB/s ±20% 2000 MB/s ±20% Operating Temperature 32° to 158°F (0° to 70°C) [ambox temp] Features TCG Opal 2.0; TRIH; L1.2 Features TCG Opal 2.0; TRIH; L1.2 Note: For storage drives, GB + billion bytes. TB = 1 trillion bytes. Actual for windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 Kore: For storage drives, GB + billion bytes. TB = 1 trillion bytes. Actual for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 Kore: For storage drives, GB + billion bytes. TB = 1 trillion bytes. Actual for Windows 10) is reserved for system recovery software. Solid State Drive Form Factor M.2 2280 Kore: For storage drives, GB + billion bytes. TB = 1 trillion bytes. TB = 1 trillion bytes. Solid State Drive Form Factor M.2 2280 Kore: For Storage drives, GB + billion bytes. Width		Capacity	256GB	
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.02 lb (10 g)InterfacePCIe NVMe Gen4X4Performance4000 MB/s ±20%Operating Temperature32° to 158°F (0° to 70°C) [amber temp]FeaturesVCG Opal 2.0; TRIM; L1.2FeaturesNote: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.S12GB PCIe-4x4 2280Form FactorN.22280NVME Self Encrypted OPAL2 Three Layer Cell NAND TypeTLCNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Width0.92 lb (10 g)Height0.02 lb (10 g)Width0.92 lb (10 g)Height0.02 lb (10 g)Hei		NAND Type	TLC	
Neight0.02 b(0.0 g)InterfacePCI NVM Gen4X4PerformanceMaimu Sequential RealLogical Blocks50.0118,192Operating Temperateu2° to 158°F (0° to 70°C) [John State Brive	Height	0.09 in (2.3 mm)	
Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write 4000 MB/s ±20% 2000 MB/s ±20% Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features TCG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cell Gapacity S12GB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.87 in (22 mm) Width 0.02 lb (10 g) Interface PCIe NVME Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write Motight 0.02 lb (10 g) Interface S100 MB/s ±20% Note: For Storage drives, SI S100 MB/s ±20% S100 MB/s ±20% Koight 0.02 lb (10 g) Interface S100 MB/s ±20% Note: Gaige Blocks 1,000,215,215 S100 MB/s ±20% S100 MB/s ±20%		Width	0.87 in (22 mm)	
PerformanceMaximum Sequential Read 4000 MB/s ±20%Maximum Sequential Write 2000 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesTCG Opal 2.0; TRIM; L1.2Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.\$12GB PCle-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State DriveForm FactorKurden Maximum Sequential Vite Height0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMaximum Sequential Read 6400 MB/s ±20%Adom MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Capacing Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)	
4000 MB/s ±20% 2000 MB/s ±20% Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [amber temp] Features CG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB + billion bytes. TB = 1 trillion bytes. Actual formatic capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cells Capacity 512GB NAND Type TLC		Interface	PCIe NVMe Gen4X4	
Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambi=nt temp] Features TCG Opal 2.0; TRIN; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cells AND Type TLC NAND Type TLC Height N40 type 0.09 in (2.3 mm) SUB (10 g) Width 0.37 in (22 mm) SUB (10 g) Width 0.21 b(10 g) SUB (10 g) Interface Performance Maximum Sequential Real Maximu Sequential Real Maximum Sequential Write Guo MB/s ±20% 350 OMB/s ±20%		Performance	Maximum Sequential Read	Maximum Sequential Write
Operating Temperature 32° to 158°F (0° to 70°C) [amittemp] Features CG Opal 2.0; TRIN; L1.2 Note: For storage drives, GB - 1 billion bytes, TB = 1 trillion bytes, Actual formatted capacity is less. J = 5 GB (for Windows 10) is reserved for system recovery software. S12GB PCIe-4x4 2280 Form Factor M.2 2280 NWE Self Encrypted OPAL2 Three Layer Cell And Type 12 GB NAD Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Immer Actual Mittem Actual Mitte			4000 MB/s ±20%	2000 MB/s ±20%
Features TCG Opal 2.0; TRIM; L1.2 Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. \$12GB PCIe-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Form Factor M.2 2280 NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write 6400 MB/s ±20% 3500 MB/s ±20% 3500 MB/s ±20% Logical Blocks 1,000,215,215 32° to 158°F (0° to 70°C) [ambitut temp]		Logical Blocks	500,118,192	
S12GB PCIe-4x4 2280 Form Factor M.2 2280 S0MVME Self Encrypted Capacity S12GB OPAL2 Three Layer Cell Capacity S12GB Solid State Drive Capacity S12GB Width 0.09 in (2.3 mm) Image: Cell Signed Signe		Operating Temperature	32° to 158°F (0° to 70°C) [amb	ient temp]
S12GB PCle-4x4 2280 Form Factor M.2 2280 NVME Self Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280 Solid State Drive Capacity 512GB NAND Type TLC NAND Type Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCle NVMe Gen4X4 Performance Maximum Sequential Read Maximum Sequential Write 6400 MB/s ±20% 3500 MB/s ±20% 3500 MB/s ±20%		Features	TCG Opal 2.0; TRIM; L1.2	
NVME Self Encrypted OPAL2 Three Layer Cell Solid State DriveCapacity512GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential Write6400 MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperatue32° to 158°F (0° to 70°C) [=++++++++++++++++++++++++++++++++++++			formatted capacity is less. Up	
OPAL2 Three Layer Cell Solid State DriveNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential Write6400 MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambut temp]		Form Factor	M.2 2280	
Solid State DriveNAND TypeItcHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential Write6400 MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [arrent temp]		Capacity	512GB	
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential WriteLogical Blocks1,000,215,2153500 MB/s ±20%Operating Temperature32° to 158°F (0° to 70°C) [arrur temp]		NAND Type	TLC	
Weight0.02 lb (10 g)InterfacePCle NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential Write6400 MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [arrtimeter]		Height	0.09 in (2.3 mm)	
InterfacePCIe NVMe Gen4X4PerformanceMaximum Sequential ReadMaximum Sequential Write6400 MB/s ±20%3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)	
PerformanceMaximum Sequential Read 6400 MB/s ±20%Maximum Sequential Write 3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)	
6400 MB/s ±20% 3500 MB/s ±20% Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen4X4	
Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Performance	-	-
		Logical Blocks	1,000,215,215	
FeaturesTCG Opal 2.0; TRIM; L1.2		Operating Temperature	32° to 158°F (0° to 70°C) [amb	vient temp]
		Features	TCG Opal 2.0; TRIM; L1.2	



Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual

Technical Specifications – Storage

		formatted capacity is less. Up system recovery software.	to 35 GB (for Windows 10) is reserved for	
4TB PCIe-4x4 2280 NVMe	Form Factor	M.2 2280		
Three Layer Cell double-	Capacity	4TB		
sided M.2 Solid State Drive	NAND Type	TLC		
DIIVE	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	15g		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		Up to 6000 MB/s	Up to 6000 MB/s	
	Logical Blocks	8,001,594,720		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite 2.0; TRIM; L1.2		
			1 billion bytes. TB = 1 trillion bytes. Actual to 35 GB (for Windows 10) is reserved for	



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel AX211 Wi-Fi 6E +BT 5.2 M.2 160MHz CNVi WLAN vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz • 5.955 – 6.415 GHz • 6.435 – 6.515 GHz • 6.535 – 6.875 GHz • 6.895 – 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Noaming	



Technical Specifications – Networking

Output Power ²	• 802.11g • 802.11a • 802.11n • 802.11n	: +17dBm minimum : +16dBm minimum : +17dBm minimum HT20(2.4GHz) : +14dBm minimum HT40(2.4GHz) : +13dBm minimum	
	• 802.11n • 802.11ac • 802.11ac • 802.11ac • 802.11ac • 802.11ac	HT20(5GHz) : +14dBm minimum HT40(5GHz) : +13dBm minimum : VHT80(5GHz) : +10dBm minimum : VHT160(5GHz) : +10dBm minimum < HE40(2.4GHz) : +12dBm minimum < HE80(5GHz) : +10dBm minimum < HE160(5GHz) : +10dBm minimum	
Power Consumption	• Receive mode 1.6 • Idle mode (PSP) 1 • Idle mode 50 mW	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW 	
Power Management	ACPI and PCI Expres 802.11 compliant p	ss compliant power management ower saving mode	
Receiver Sensitivity ³ Antenna Type	 802.11b, 11Mbps 802.11a/g, 6Mbps 802.11a/g, 54Mbp 802.11n, MCS07 : 802.11n, MCS15 : 802.11ac, MCS0(V 802.11ac, MCS9(V 802.11ac, MCS9(V 802.11ax, MCS11(802.11ax, MCS11(802.11ax, MCS11(
		al band 2.4/5 GHz antennas are provided to th AN MIMO communications and Bluetooth	
Form Factor	PCI-Express M.2 Mi		
Dimensions	1. Type 1216: 1.67	x 12.0 x 16.0 mm	
Weight	2. Type 1216: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
	Operating Non-	0 to 10,000 ft (3,048 m)	





Technical Specifications – Networking

Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
	LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE
*Wi-Fi 6E requires a Wi-Fi 6E router	LE Long Range , sold separately, and Windows 11 to function in the 6GHz band.

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, and Windows 11 to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Wireless LAN Standards

IEEE 802.11a IEEE 802.11b



Technical Specifications – Networking

Intel AX211 Wi-Fi 6E +BT 5.2 M.2 160MHz CNVi WLAN non-vPro		IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz • 5.955 – 6.415 GHz • 6.435 – 6.515 GHz • 6.535 – 6.875 GHz • 6.895 – 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11 compliant roaming between access points 802.11b : +17dBm minimum 802.11a : +17dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT40(5GHz) : +13dBm minimum



Technical Specifications – Networking

	• 802.11ac VI • 802.11ax HI • 802.11ax HI • 802.11ax HI	HT80(5GHz) : +10dBm minimum HT160(5GHz) : +10dBm minimum E40(2.4GHz) : +12dBm minimum E80(5GHz) : +10dBm minimum E160(5GHz) : +10dBm minimum	
Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW 		
Power Management	ACPI and PCI Express of 802.11 compliant pow	compliant power management ver saving mode	
Receiver Sensitivity ³ Antenna Type	 •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum •802.11a/g, 6Mbps : -86dBm maximum •802.11a/g, 54Mbps : -72dBm maximum •802.11n, MCS07 : -67dBm maximum •802.11n, MCS15 : -64dBm maximum •802.11ac, MCS0(VHT80) : -84dBm maximum •802.11ac, MCS9(VHT80) : -59dBm maximum •802.11ac, MCS9(VHT60) : -58.5dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE160): -53.5dBm maximum •802.11ax, MCS11(HE160): -53.5dBm maximum •802.11ax, MCS11(HE160): -53.5dBm maximum 		
		and 2.4/5 GHz antennas are provided to the MIMO communications and Bluetooth	
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	1. Type 1216: 1.67 x 1	2.0 x 16.0 mm	
Weight	2. Type 1216: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non- operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OF	FF; LED White – Radio ON	
HP Integrated Module with Blueto	oth 4.0/4.1/4.2/5.0/5	.1/5.2 Wireless Technology	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	BLE : 1 Mbps data rate	rate; throughput up to 2.17 Mbps e; throughput up to 0.2 Mbps Connection Oriented links up to 3, 64 kbps,	



Technical Specifications – Networking

	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Security & Manageability

Intel[®] vPro[™] support with appropriate Intel[®] chipset components

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, and Windows 11 to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Near Field Communications Controller (optional)

Dimensions (L x W Module 25 mm by 10 mm by 2.0 mm **x H)**



Technical Specifications – Networking

Chipset	NPC300			
System interface	120			
NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 ECMA-320 NFCIP-2		itor	
NFC Forum Support	Tag Type 1, Type 2,	, Type3 and Type	4, NFCIP-1 and NFCIP-2	
Reader (PCD-VCD) Mode	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz ca	rds		
Card Emulation (PICC-				
VICC) Mode	ISO/IEC 14443 B an MIFARE	d B'		
	FeliCa			
Frequency	13.56 MHz			
NFC Modes Supported	Reader/Writer, Pee	r-to-Peer		
Raw RF Data Rates	106, 212, 424, 848	106, 212, 424, 848 kbps		
Operating temperature	0°C to 70°C			
Storage temperature	-20°C to 125°C			
Humidity	10-90% operating 5-95% non-operati	ng		
Supply Operating voltage	4.35 to 5.25 Volts			
I/O Voltage	1.8V or 3.3V			
Power Consumption	Booster enable,	VBAT= 3.3V,		
	VCC_BOOST = 5V)	Polling	7.3 mA	
	Mode Power Consumption,		Total 283.8 mA	
	Typical	Tag Type 1 Detected Test	Net Module 236.8 mA Total 288.8 mA	
		Tag Type 2	Net Module 241.8 mA	
		Detected Test	Total 287.7 mA	
		Tag Type 3	Net Module 240.7 mA	
		Detected Test		
Antonno		Tag Type 4	Net Module 235.3 mA	
Antenna	Antenna connector external to module	•	connector FPC. Antenna matching is	

AUDIO

HD Stereo Codec Audio I/O Ports Realtek ALC3315 Headset: CTIA only and Headphone-out



Technical Specifications – Networking

Internal Speaker Amplifier	Cirrus Logic High-Efficiency Boosted Class D Amplifier
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio. Following MSFT Behaviour
Sampling	DAC: 44.1k/48kHz ADC: 48kHz
Wavetable Syntheses	
Analog Audio	Support 3.5mm Headset: CTIA only and Headphone-out
# of Channels on Line- Out	
Internal Speaker	Yes

FINGERPRINT READER

Sensor vendor	Synaptics FS7604
Sensor type	Capacitive
DPI resolution	363DPI
Scan area	7.4x6mm sensor area
False Rejection Rate	<1%
False Acceptance Rate	1:50K FAR
Mobile Voltage Operation	Mobile Voltage Operation: 3.0V to 3.6V
Operating Temperature	Operating Temperature: 0~60°C
Current Consumption Image	Current Consumption Image: 100mA Max
Low Latency Wait For Finger	Low Latency Wait For Finger: 260 uA
Capture Rate	Capture Rate: <30msec per image
ESD Resistance	ESD Resistance: IEC 61000-4-2 4B (+/-15KV)
Detection Matrix	Detection Matrix: 363 dpi / 7.4x6mm sensor area

POWER

AC Adapter 65 Watt nPFC	Dimensions	138x66x22mm		
Slim USB type C Straight 1.8m	Weight	unit: 325g +/- 10g		
1.011	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	2.7 A at 90 Vac and Maximum Load	
	Output	Output power	150W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<16.0A	
	Connector	C6		
		DC Plug	4.5mm Barrel Type	



Technical Specifications – Networking

Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	5% to 95%
	Storage Humidity	5% to 95%
EMI and Safety Certifications	* Worldwide safety standa 1 and/or EN62368-1, UL60 Agency approvals - C-UL-L B, CISPR32 Class B, CCC, N	with LVD and EMC directives rds - IEC60950-1 and/or IEC62368-1, EN60950- 0950-1 and/or UL62368-1, Class1, SELV; JS, NORDICS, DENAN, EN55032 Class B, FCC Class DM-001 NYCE. Irs at 25°C ambient condition.



Technical Specifications – Power

AC Adapter 120 Watt Smart PFC Slim Barrel	Dimensions	138x68.5x25.4mm		
4.5mm Right Angle -	Weight	unit: 350g +/- 10g	00% at 115 Mag and 00% at 220Mag	
Delphin	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac	
		Input frequency range	47 ~ 63 Hz	
	• • •	Input AC current	1.7 A at 90 Vac and Maximum Load	
	Output	Output power	120W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<18.0A	
	Connector	C6		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	5% to 95%	
		Storage Humidity	5% to 95%	
	EMI and Safety Certifications	* Worldwide safety standa 1 and/or EN62368-1, UL6 Agency approvals - C-UL-I B, CISPR32 Class B, CCC, N	e with LVD and EMC directives ards - IEC60950-1 and/or IEC62368-1, EN60950- 0950-1 and/or UL62368-1 , Class1, SELV; US, NORDICS, DENAN, EN55032 Class B, FCC Class OM-001 NYCE. urs at 25°C ambient condition.	
Battery 6 Cell WHr 83	Dimensions (H x W x L)	8.7 x 316.1 x70.2mm (0.3	342 x 12.44 x 2.763 inch)	
Long Life -PL Fast Charge		0.31kg (0.683lb)		
	Cells/Type	6cell Lithium-Ion Polymer cell / 685257		
	Energy	Voltage	11.58V	
		Amp-hour capacity	7.170Ah	
		Watt-hour capacity	83Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
	-	Operating (Discharging)	14° to 122° F (-10° to 60° C)	
	Fuel Gauge LED	NA		
	Warranty	Refer to http://www.hp.com/support/batterywarranty/ for battery warranty information.		
	Optional Travel Battery Available	N/A		
	*Batteries have a default (1-year or 3-year limited w		xcept for Long Life batteries which will have same	



ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT[□] Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified IEC 60601-1-2:2014 EN60601-1-2: 2015 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*
Sustainable Impact Specifications	 Ocean-bound plastic in Speaker Box¹ 35% post-consumer recycled plastic² External Power Supply 90% Efficiency Low halogen³ Outside Box and corrugated cushions are 100% sustainably sourced and recyclable⁴ Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable⁵ Bulk packaging available
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".
Energy Consumption (in accordance with US ENER(GY

STAR [®] test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	6.25 W	6.11 W	6.13 W
Normal Operation (Long idle)	1.42 W	1.5 W	1.4 W
Sleep	1.42 W	1.5 W	1.4 W
Off	0.4 W	0.42 W	0.4 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	21.4 BTU/hr	20.9 BTU/hr	21 BTU/hr
Normal Operation (Long idle)	4.9 BTU/hr	5.1 BTU/hr	4.8 BTU/hr
Sleep	4.9 BTU/hr	5.1 BTU/hr	4.8 BTU/hr
Off	1.4 BTU/hr	1.4 BTU/hr	1.4 BTU/hr



***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Optical Drive – Sequential reads Longevity and Upgrading	This product can be upgraded, possibly extend features and/or components contained in the		Sound Pressure (L _{pAm} , decibels) 13.7 14.9 31.4 ding its useful life by several years. Upgradeable anty period and or for up to "5" years after the end	
Additional Information	directiv This HP Equipm This pro Drinking This pro www.ep Plastics and ISO	e - 2011/65/EC. product is designed to comply with ent (WEEE) Directive – 2002/96/EC. oduct is in compliance with California g Water and Toxic Enforcement Act oduct is in compliance with the IEEE peat.net parts weighing over 25 grams used	Proposition 65 (State of California; Safe of 1986). 1680 (EPEAT) standard at the Gold level, se in the product are marked per ISO11469	!e
Packaging Materials	External:	PAPER/Corrugated	295 g	
		PAPER/Molded Pulp	170 g	
	Internal:	PLASTIC/Polyethylene low density	- LDPE 10 g	
	The plastic pack	kaging material contains at least 10	0% recycled content.	
	The corrugated paper pack		kaging materials contains at least 35.6% recycled content.	
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.			
	We believe the RoHS directive and similar laws play an important role in promoting industry- wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			
		luding PVC, BFRs, and certain phtha	lates—in future RoHS legislation that	
	pertains to elect We met our volu requirements fo	luding PVC, BFRs, and certain phtha rical and electronics products. ntary objective to achieve worldwid r virtually all relevant products by J	-	e



Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and
RecyclingHP offers end-of-life HP product return and recycling programs in many geographic areas. To
recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
HP sales office. Products returned to HP will be recycled, recovered or disposed of in a
responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.



These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:			
	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html			
	Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:			
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and			
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf			
Footnotes	¹ Percentage of ocean-bound plastic contained in each component varies by product ² Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018			
	standard. ³ External power supplies, WWAN modules, power cords, cables and peripherals excluded. ⁴ 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.			
	⁵ Fiber cushions made from 100% recycled wood fiber and organic materials.			



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Date of change:	Version History:		Description of change:
March 29, 2022	From v1 to v2	Changed	DRIVE CONTROLLERS and Power sections
March 31, 2022	From v2 to v3	Changed	PROCESSOR section
April 13, 2022	From v3 to v4	Changed	ENVIRONMENTAL DATA and Power sections
April 21, 2022	From v4 to v5	Changed	DRIVE CONTROLLERS and Power sections
May 2, 2022	From v5 to v6	Changed	MEMORY section
May 9, 2022	From v6 to v7	Changed	STORAGE AND DRIVES and DRIVE CONTROLLERS sections
May 17, 2022	From v7 to v8	Changed	PORTS/SLOTS section
May 20, 2022	From v8 to v9	Changed	KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS section
June 7, 2022	From v9 to v10	Changed	PROCESSOR section

